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EXAMINER	
WALFORD, NATALIE K	

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2879	

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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No.	Applicant(s)	
	10/718,640	SHIGEMURA ET AL.	
	Examiner	Art Unit	
	Natalie K. Walford	2879	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1)☒ Responsive to communication(s) filed on *21 May 2007*.

2a)☐ This action is **FINAL**. 2b)☒ This action is non-final.

3)☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4)☒ Claim(s) *1-41 and 49-56* is/are pending in the application.

4a) Of the above claim(s) *7-9,24,25,31-33 and 39-41* is/are withdrawn from consideration.

5)☐ Claim(s) _____ is/are allowed.

6)☒ Claim(s) *1-6,10-23,26-30,34-38 and 49-56* is/are rejected.

7)☐ Claim(s) _____ is/are objected to.

8)☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9)☐ The specification is objected to by the Examiner.

10)☒ The drawing(s) filed on *24 November 2003* is/are: a)☒ accepted or b)☐ objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11)☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12)☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a)☒ All b)☐ Some * c)☐ None of:

1.☒ Certified copies of the priority documents have been received.

2.☐ Certified copies of the priority documents have been received in Application No. _____.

3.☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) ☒ Notice of References Cited (PTO-892)
2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) ☐ Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date _____.
4) ☐ Interview Summary (PTO-413) Paper No(s)/Mail Date. _____.
5) ☐ Notice of Informal Patent Application
6) ☐ Other: _____.

DETAILED ACTION

Response to Amendment

Applicant's request for reconsideration of the finality of the rejection of the last Office action is persuasive and, therefore, the finality of that action is withdrawn.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

> A person shall be entitled to a patent unless –
>
> (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-6, 10-23, 26-30, 34-38, and 49-56 are rejected under 35 U.S.C. 102(b) as being anticipated by Himeshima et al. (US 6,469,439).

Regarding claim 1, Himeshima discloses an evaporation mask (item 31) formed of a thin film in figures 35 and 36, wherein the evaporation mask is drawn taut by application of tension (item 22) and comprises: at least one mask unit (area around item 32), comprising: a plurality of main apertures (item 32), and a plurality of first dummy apertures (item 32) formed adjacent to outermost ones of the main apertures in a direction in which tension is applied to the evaporation mask.

Regarding claim 2, Himeshima discloses the evaporation mask of claim 1, wherein the main apertures form an effective deposition area, and the first dummy apertures form an ineffective deposition area (see Abstract).

Regarding claim 3, Himeshima discloses the evaporation mask of claim 2, wherein at least one of the first dummy apertures is formed parallel to the main apertures (see FIG. 35), and at least another one of the first dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 4, Himeshima discloses the evaporation mask of claim 2, comprising at least two mask units (area around item 32), and further comprising a plurality of second dummy apertures (item 32) formed outside and adjacent to the outermost mask units in the direction in which tension is applied to the evaporation mask.

Regarding claim 5, Himeshima discloses the evaporation mask of claim 4, wherein the second dummy apertures are formed outside the effective deposition areas where the mask units are formed (see Abstract).

Regarding claim 6, Himeshima discloses the evaporation mask of claim 4, wherein at least one of the second dummy apertures is formed parallel to the main apertures of the mask units (see FIG. 35), and at least another one of the second dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 10, Himeshima discloses a method of manufacturing an organic electroluminescent (EL) device, the method comprising: forming first electrodes (item 2) on a substrate (item 1); disposing an evaporation mask (item 31) to form an organic film (item 6) over the substrate, the evaporation mask drawn taut by application of tension (item 22) and having at least one mask unit (area around item 32), the mask unit comprising a plurality of main apertures (item 32) and a plurality of first dummy apertures (item 32) formed adjacent to outermost ones of the main apertures in a direction in which tension is applied to the evaporation mask; forming the

organic film comprising an effective luminescent area to cover at least the first electrodes by evaporating an organic material containing an organic luminescent material (item 6) through the main apertures (see FIG. 16), and forming a first dummy pattern area (item 32) outside the effective luminescent area through the first dummy apertures; forming second electrodes (item 8) on the organic film so that the effective luminescent area is formed at an area where the first and second electrodes overlap; and sealing the resulting structure (see FIG. 2).

Regarding claim 11, Himeshima discloses the method of claim 10, wherein at least one of the first dummy apertures is formed parallel to the main apertures (see FIG. 35), and at least another one of the first dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 12, Himeshima discloses the method of claim 10, wherein at least two organic EL devices are manufactured in a single process (see Abstract), and the evaporation mask comprises at least two mask units (area around item 32), through each of which the organic film of a single organic EL device (item 6) can be deposited, and a plurality of second dummy apertures (item 32) outside and adjacent to outermost ones of the mask units in the direction in which tension is applied to the evaporation mask.

Regarding claim 13, Himeshima discloses the method of claim 12, wherein the second dummy apertures of the evaporation mask are located outside the effective luminescent areas of the organic EL devices that are deposited by the outermost mask units adjacent to the second dummy apertures (see FIG. 35).

Regarding claim 14, Himeshima discloses the method of claim 12, wherein at least one of the second dummy apertures is formed parallel to the main apertures of the mask units (see FIG.

35), and at least another one of the second dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 15, Himeshima discloses the method of claim 10, wherein in forming the second electrodes (see FIG. 27), an evaporation mask (item 31) to form the second electrodes is disposed over the substrate, the evaporation mask drawn taut by application of tension (item 31) and having at least one mask unit (area around item 32), the mask unit comprising a plurality of main apertures (item 32) and a plurality of first dummy apertures (item 32) formed adjacent to the outermost main apertures in the direction in which tension is applied to the evaporation mask, the second electrodes (item 8) are formed on the effective luminescent area through the main apertures, and a second dummy pattern area is formed outside the effective luminescent area through the first dummy apertures (see FIG. 27).

Regarding claim 16, Himeshima discloses the method of claim 15, wherein at least one of the first dummy apertures is formed parallel to the main apertures (see FIG. 35), and at least another one of the first dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 17, Himeshima discloses the method of claim 15, wherein at least two organic EL devices are manufactured in a single process (see Abstract), and the evaporation mask comprises at least two mask units (area around item 32), through each of which the second electrodes of a single organic EL device can be deposited, and a plurality of second dummy apertures (item 32) outside and adjacent to the outermost mask units in the direction in which tension (item 22) is applied to the evaporation mask.

Regarding claim 18, Himeshima discloses the method of claim 17, wherein the second dummy apertures are located outside the effective luminescent areas of the organic EL devices that are deposited by the outermost mask units adjacent to the second dummy apertures (see FIG. 18 and 35).

Regarding claim 19, Himeshima discloses the method of claim 17, wherein at least one of the second dummy apertures is formed parallel to the main apertures of the mask units (see FIG. 35), and at least another one of the second dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 20, Himeshima discloses the method of claim 10, wherein at least two organic EL devices are manufactured in a single process (see Abstract), the second electrodes are formed using an evaporation mask drawn taut by application of tension (see FIG. 27) and having at least two mask units (area around item 32), through which the second electrodes of the organic EL devices can be deposited, and the evaporation mask comprises a plurality of second dummy apertures (item 32) outside and adjacent to outermost mask units in the direction in which tension (item 22) is applied to the evaporation mask.

Regarding claim 21, Himeshima discloses the method of claim 20, wherein the second dummy apertures are located outside the effective luminescent areas of the organic EL devices that are deposited by the outermost mask units adjacent to the second dummy apertures (see FIG, 27).

Regarding claim 22, Himeshima discloses the method of claim 20, wherein at least one of the second dummy apertures is formed parallel to the main apertures of the mask units (see FIG.

35), and at least another one of the second dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 23, Himeshima discloses a method of manufacturing an organic EL device, the method comprising: forming first electrodes (item 2) for an organic EL device on a substrate (item 1); disposing an evaporation mask (item 31) to form an organic film (item 6) over the substrate, the evaporation mask drawn taut by application of tension (item 22) and including at least two mask units (area around item 32) each comprising a plurality of main apertures (item 32) and a plurality of second dummy apertures (item 32) formed outside and adjacent to outermost ones of the mask units in a direction in which tension is applied to the evaporation mask; forming the organic film (item 6) comprising an effective luminescent area to cover at least the first electrodes by evaporating an organic material containing an organic luminescent material (item 6) through the main apertures of each of the mask units (See FIG. 16); forming second electrodes (item 8) on the organic film so that the effective luminescent area is formed at an area where the first and second electrodes overlap; and sealing the resulting structure (see FIG. 2).

Regarding claim 26, Himeshima discloses the method of claim 23, wherein in forming the second electrodes, an evaporation mask (item 31) to form the second electrodes is disposed over the substrate (See FIG. 27), the evaporation mask drawn taut by application of tension (item 22) and including at least two mask units (area around item 32), the mask units each comprising a plurality of main apertures (item 32) and a plurality of first dummy apertures (item 32) formed adjacent to the outermost main apertures in the direction in which tension is applied to the evaporation mask, the second electrodes are formed on each of the effective luminescent areas

through the main apertures (see FIG. 27), and a second dummy pattern area is formed outside each of the effective luminescent areas through the first dummy apertures (see FIG. 27).

Regarding claim 27, Himeshima discloses the method of claim 26, wherein at least one of the first dummy apertures is formed parallel to the main apertures (see FIG. 35), and at least another one of the first dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 28, Himeshima discloses the method of claim 26, wherein the evaporation mask comprises a plurality of second dummy apertures (item 32) outside and adjacent to the outermost mask units in the direction in which tension (item 22) is applied to the evaporation mask.

Regarding claim 29, Himeshima discloses the method of claim 28, wherein the second dummy apertures of the evaporation mask are located outside the effective luminescent areas of the organic EL devices that are deposited by the outermost mask units adjacent to the second dummy apertures (see FIG. 35).

Regarding claim 30, Himeshima discloses the method of claim 28, wherein at least one of the second dummy apertures is formed parallel to the main apertures of the mask units (see FIG. 35), and at least another one of the second dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 34, Himeshima discloses a method of manufacturing an organic EL device, the method comprising: forming first electrodes (item 2) on a substrate (item 1) in a predetermined pattern; forming an organic film (item 6) comprising an effective luminescent area to cover at least the first electrodes by evaporating an organic material containing an organic

luminescent material (item 6); disposing an evaporation mask (item 31) to form second electrodes (item 8) over the organic film, the evaporation mask drawn taut by application of tension (item 22) and comprising a plurality of main apertures (item 32) and a plurality of first dummy apertures (item 32) formed adjacent to outermost ones of the main apertures in a direction in which tension is applied to the evaporation mask (see FIG. 35); forming the second electrodes through the main apertures so that the effective luminescent area is formed at an area where the first and second electrodes overlap (see FIG .27), and forming a second dummy pattern area outside the effective luminescent area through the first dummy apertures; and sealing the resulting structure (see FIG. 27).

Regarding claim 35, Himeshima discloses the method of claim 34, wherein at least one of the first dummy apertures is formed parallel to the main apertures (see FIG. 35), and at least another one of the first dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 36, Himeshima discloses the method of claim 34, wherein at least two organic EL devices are manufactured in a single process (see Abstract), and the evaporation mask comprises at least two mask units (area around item 32), through each of which the second electrodes of a single organic EL device can be deposited (see FIG. 27), and a plurality of second dummy apertures (item 32) outside and adjacent to outermost ones of the mask units in the direction in which tension (item 22) is applied to the evaporation mask.

Regarding claim 37, Himeshima discloses the method of claim 36, wherein the second dummy apertures of the evaporation mask are located outside the effective luminescent areas of

the organic EL devices that are deposited by the outermost mask units adjacent to the second dummy apertures (see FIG. 27).

Regarding claim 38, Himeshima discloses the method of claim 36, wherein at least one of the second dummy apertures is formed parallel to the main apertures of the mask units (see FIG. 35), and at least another one of the second dummy apertures is formed perpendicular to the main apertures (see FIG. 35).

Regarding claim 49, Himeshima discloses an evaporation mask (item 31) formed of a thin film, wherein the evaporation mask is drawn taut by application of tension (item 22), the evaporation mask comprising: at least one mask unit (area around item 32) comprising: at least one main aperture (item 32), and at least one first dummy aperture (item 32) formed adjacent to an outermost at least one main aperture in a direction in which tension (item 22) is applied to the evaporation mask.

Regarding claim 50, Himeshima discloses the evaporation mask of claim 49, further comprising at least one second dummy aperture (item 32) formed outside and adjacent to the outermost at least one mask unit in the direction in which tension (item 22) is applied to the evaporation mask.

Regarding claim 51, Himeshima discloses a mask unit for an evaporation mask in figure 35, comprising: a main aperture (item 32); and a dummy aperture (item 32); wherein the dummy aperture prevents the main aperture from being deformed by tension (item 22) applied to the evaporation mask.

Regarding claim 52, Himeshima discloses the evaporation mask of claim 1, wherein a length of each of the first dummy apertures is equal to a length of each of the main apertures (see FIG. 35).

Regarding claim 53, Himeshima discloses the method of claim 10, wherein a length of each of the first dummy apertures is equal to a length of each of the main apertures (see FIG. 35).

Regarding claim 54, Himeshima discloses the method of claim 34, wherein a length of each of the first dummy apertures is equal to a length of each of the main apertures (see FIG. 35).

Regarding claim 55, Himeshima discloses the evaporation mask of claim 49, wherein a length of each of the at least one first dummy aperture is equal to a length of each of the at least one main aperture (see FIG. 35).

Regarding claim 56, Himeshima discloses the mask unit of claim 51, wherein a length of the dummy aperture is equal to a length of the main aperture (see FIG. 35).

Response to Arguments

Applicant's arguments with respect to claims 1-56 have been considered but are moot in view of the new ground(s) of rejection.

Contact Information

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Natalie K. Walford whose telephone number is (571)-272-6012. The examiner can normally be reached on Monday-Friday, 8 AM - 4:30 PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nimesh Patel can be reached on (571)-272-2457. The fax phone number for the organization where this application or proceeding is assigned is (571)-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

nkw

10/28/07

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